L	Hits	Search Text	DB	Time stamp
Number	298253	mask	USPAT;	2002/04/18
1	298253	mask	EPO; JPO; DERWENT	17:32
2	10145	conformable	USPAT;	2002/04/18
	10113	00.1202.11.0320	EPO; JPO; DERWENT	17:32
3	1646757	substrate workpiece wafer	USPAT;	2002/04/18
3	1040/3/	Substrace workprece water	EPO; JPO; DERWENT	17:33
4	613481	deform\$5	USPAT;	2002/04/18
1	015401	delolinyo	EPO; JPO; DERWENT	17:34
5	621248	conformable deform\$5	USPAT;	2002/04/18
	021210		EPO; JPO; DERWENT	17:34
6	8338	mask and (substrate workpiece wafer) and	USPAT;	2002/04/18
	0330	(conformable deform\$5)	EPO; JPO;	17:34
7	48327	electroplat\$3	DERWENT USPAT;	2002/04/18
7	40327	electiobiacia	EPO; JPO;	17:34
	3305	 electrolytic adj deposition	DERWENT USPAT;	2002/04/18
8	3295	electrolytic adj deposition	EPO; JPO;	17:34
			DERWENT	1,.51
9	746	electrolytically adj depositing	USPAT;	2002/04/18
			EPO; JPO; DERWENT	17:35
10	116	electrolytically adj deposit	USPAT;	2002/04/18
		and are the second and are the second are the secon	EPO; JPO; DERWENT	17:35
11	23714	electrodeposition	USPAT;	2002/04/18
	23711		EPO; JPO; DERWENT	17:35
12	70237	 electroplat\$3 (electrolytic adj	USPAT;	2002/04/18
12	70237	deposition) (electrolytically adj depositing) (electrolytically adj deposit) electrodeposition	EPO; JPO; DERWENT	17:35
13	1049		USPAT; EPO; JPO; DERWENT	2002/04/18 17:36
14	118105		USPAT; EPO; JPO;	2002/04/18
			DERWENT	17:36
15	662	(mask same (substrate workpiece wafer)) and (conformable deform\$5) and (electroplat\$3 (electrolytic adj deposition) (electrolytically adj	USPAT; EPO; JPO; DERWENT	2002/04/18
		depositing) (electrolytically adj deposit) electrodeposition)		
16	119319		USPAT; EPO; JPO;	2002/04/18 17:53
17	54	427/\$.ccls. and ((mask same (substrate workpiece wafer)) and (conformable	DERWENT USPAT; EPO; JPO;	2002/04/18
		deform\$5) and (electroplat\$3 (electrolytic adj deposition) (electrolytically adj depositing)	DERWENT	
		(electrolytically adj depositing)		
İ		electrodeposition))		
18	32612		USPAT; EPO; JPO; DERWENT	2002/04/18 18:08

19	34	205/\$.ccls. and ((mask same (substrate	USPAT;	2002/04/18
		workpiece wafer)) and (conformable	EPO; JPO;	18:08
		deform\$5) and (electroplat\$3	DERWENT	
		(electrolytic adj deposition)		
		(electrolytically adj depositing)	1	
		(electrolytically adj deposit)		
[electrodeposition))		